

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claims, AMEND claims, and ADD new claims, in accordance with the following:

1. (PREVIOUSLY AMENDED) A resin coating method for applying resin to a predetermined amount of resin region of on a printed wiring board, comprising the steps of:
applying a controlled amount of resin on a printed wiring board by extruding the resin from a resin application device;
spreading said resin on said printed wiring board by centrifugal force;
imaging an external appearance of the resin, as spread on the printed wiring board ;
determining a surface area of the spread and imaged resin; and
automatically adjusting the controlled amount of the resin based on the determined surface area of the spread and imaged resin .
2. (CANCELED)
3. (PREVIOUSLY AMENDED) the resin coating method as claimed in claim 1, wherein the imaging step comprises:
exposing the resin to light of a predetermined wavelength so as to fluoresce the resin;
and
separating fluorescent light so generated from light of other wavelengths to obtain a fluorescent image of the resin.
4. (CANCELED)
5. (CANCELED)
6. (PREVIOUSLY AMENDED) A resin coating method for applying resin to a predetermined amount of resin region of on a printed wiring board, comprising the steps of:

imaging an external appearance of a resin drop after the resin drop has been extruded from a nozzle of a resin application device but before the resin drop contacts the printed wiring board; and

determining a diameter of the resin drop from the image thereof;

adjusting a distance between a tip of the nozzle and the printed wiring board based on the determined diameter of the resin drop obtained in the determining step.

7. (PREVIOUSLY AMENDED) A resin coating method for applying a predetermined amount of resin to a predetermined region of on a printed wiring board, comprising the steps of:

imaging a residual amount of the resin on an extrusion nozzle of a resin application device from which the resin is expelled; and

washing the nozzle when the residual amount exceeds a predetermined amount.

8. (CANCELED)

9. (CANCELED)

10. (CANCELED)

11. (CANCELED)

12. (CANCELED)

13. (CURRENTLY AMENDED) A resin coating method as recited in claim 1, further comprising:

applying the resin by extruding same from a nozzle of ~~the~~a resin application device, the extruded resin being in the form of a ball attached ~~at a top part thereof~~ to the nozzle and displaced above and separated from the printed wiring board.

14. (PREVIOUSLY AMENDED) A resin coating method as recited in claim 13, further comprising:

lowering the nozzle so as to attach a bottom part of the ball to the printed wiring board and raising the nozzle so as to separate same from the resin ball.

15. (CANCELED)

16. (CANCELED)

17. (PREVIOUSLY ADDED) A resin coating method as recited in claim 6, further comprising:

applying the resin by extruding same from a nozzle of the resin application device, the extruded resin being in the form of a ball attached at a top part thereof to the nozzle and displaced above and separated from the printed wiring board.

18. (PREVIOUSLY ADDED) A resin coating method as recited in claim 17, further comprising:

lowering the nozzle so as to attach a bottom part of the ball to the printed wiring board and raising the nozzle so as to separate same from the ball.

19. (CURRENTLY ADDED) A resin coating method as recited in claim 18, wherein the imaging is performed by measuring the diameter of the resin ball.

20. (PREVIOUSLY ADDED) A resin coating method as recited in claim 18, further comprising:

spreading the resin ball to a uniform thickness layer; and
determining the amount of the applied resin in accordance with the measured diameter and a correlation table relating to the latter to an amount.

21. (PREVIOUSLY ADDED) A resin coating method as recited in claim 7, further comprising:

applying the resin by extruding same from the nozzle of the resin application device, the extruded resin being in the form of a ball attached at a top part thereof to the nozzle and displaced above and separated from the printed wiring board.

22. (PREVIOUSLY ADDED) A resin coating method as recited in claim 21, further comprising:

lowering the nozzle so as to attach a bottom part of the ball to the printed wiring board and raising the nozzle so as to separate same from the ball.

23. (CANCELED)

24. (CANCELED)